

Accelerating semiconductor manufacturing with deep learning

Ajay Baranwal (CDLe)









DL can solve photomask industry problems



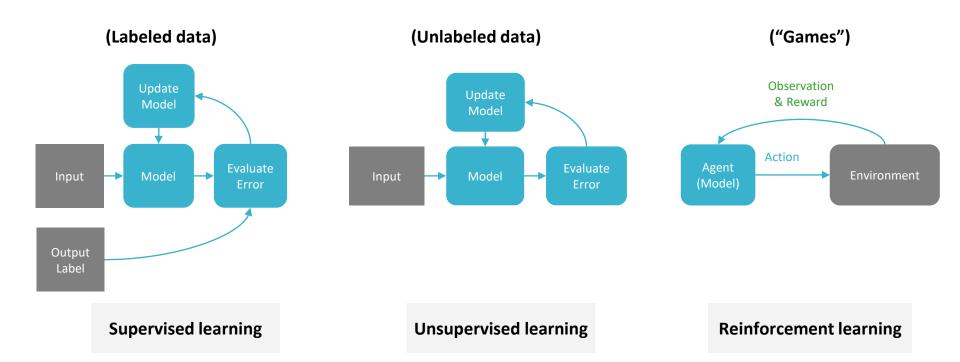
Mask inspection

Automatic defect categorization Lithography hotspot detection

Fault detection and classification

Anomalous data synthesis

Many DL techniques are used at CDLe





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Deep learning scales infinitely - Automatically

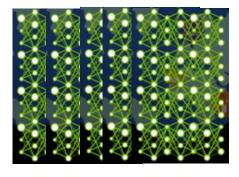
7 ExaFLOPS
60 Million
Parameters
8 Layers -> 150 Layers

20 ExaFLOPS
300 Million
Parameters
Complex Architecture

100 ExaFLOPS
8.7 Billion
Parameters
Even More Complex
Architecture







2015

2016

2017 / 2018

Mask manufacturing problems are a bit different ...

ImageNet:

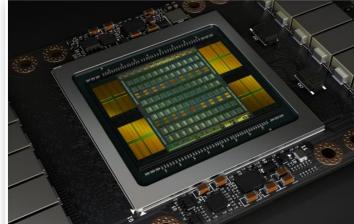
- 14.2M images
 - 1.2TB for complete dataset
- 3 σ accuracy is considered great
- Better than human is sufficient



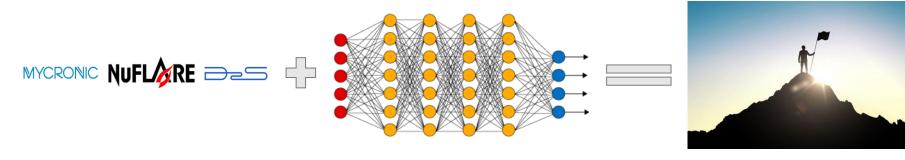
Masks:

- 540TB in 10nm pixels to write a mask
 - One Mask > 450 x ImageNet dataset
- >7 σ accuracy required





CDLe's mission is to succeed with DL breakthrough technology



CDLe is an alliance of industry leaders in electronic manufacturing

Deep learning is breakthrough technology

Success to speed up time-to-market of DL for electronic manufacturing

CDLe has achieved 10 successful projects in past year

Semiconductor photomask industry





Flat Panel Displays (FPD) mask making industry



MYCRONIC

PCB assembly line

MYCRONIC



to Center for Deep Learning in Electronics Manufacturing and its IP Members.

Two ways to be associated with CDLe

Send short terms assignees

Become partner company

Contact: Ajay Baranwal, ajay.baranwal@cdle.ai





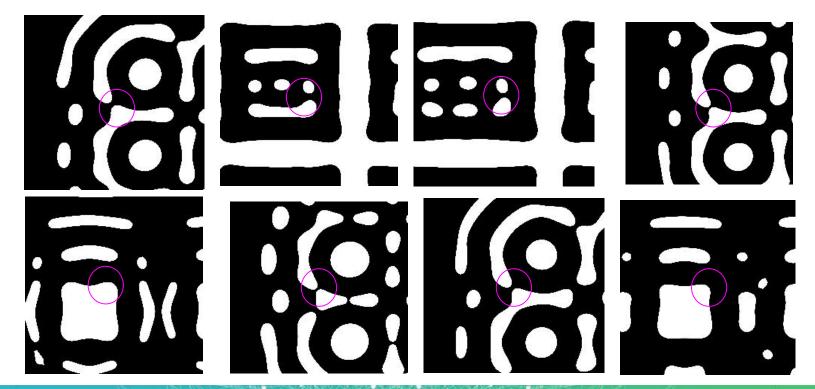
D2S: Mask rule error automatic categorization

Recommendation engines use deep learning

DL technique used: autoencoding (unsupervised DL)



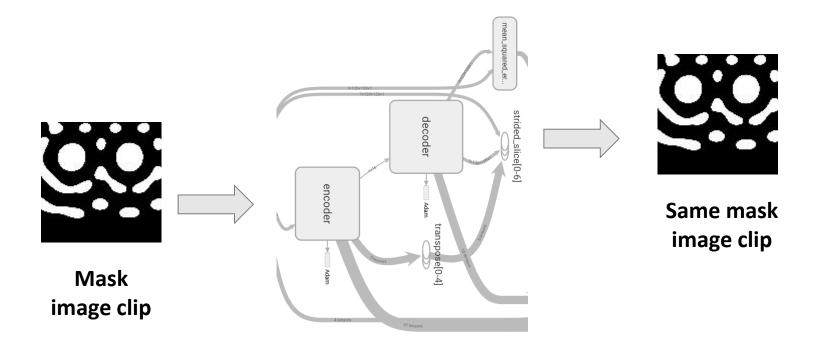
Mask rule check can generate thousands of errors Best to report similar errors together





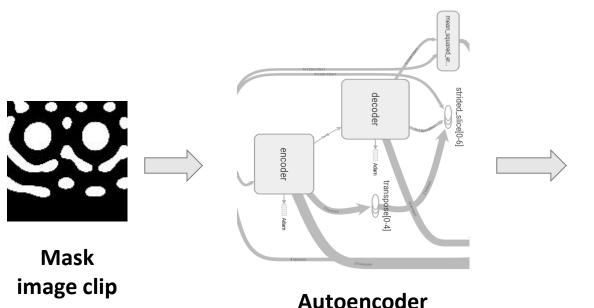
Unsupervised Autoencoder captures similarity

Uses same data as input and output for training



Unsupervised deep autoencoder captures similarity

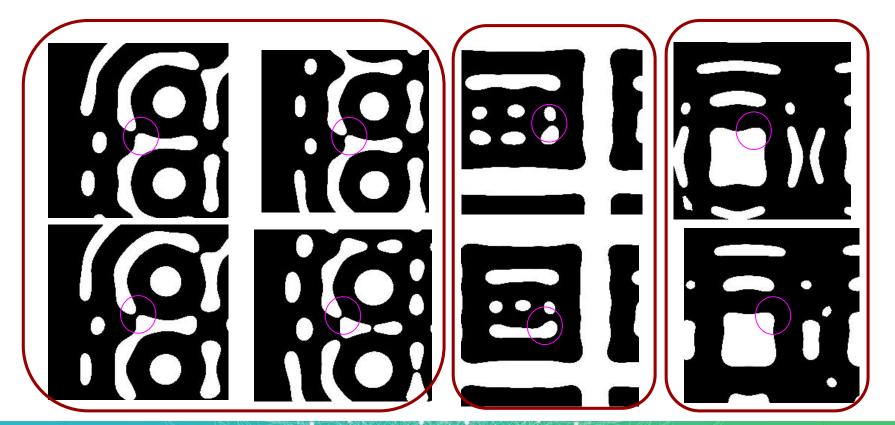
After training, creates encoding for every mask image clip



```
2.06112623e+00, -1.51410028e-01
2.68224931e+00,
                 7.21601295e+00
5.43296051e+00,
                -3.20511770e+00
2.15347147e+00,
                 8.18617404e-01
2.95589471e+00, -9.31145012e-01
6.62960470e-01, -1.27928896e+01
1.86616671e+00,
                 1.90052949e-02
2.27907753e+00, -8.11386645e-01
3.20432723e-01.
                 6.76728106e+00
2.45643973e+00.
                 7.35447228e-01
  30219030e+00
```

Series of numbers (Also called encoding)

Mask rule check groups similar errors together automatically





Mycronic: PCB component pick-and-place (PnP) error classification

Amazon Go automatic checkout uses deep learning

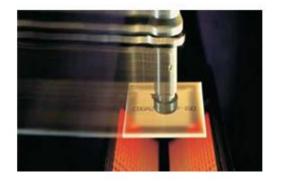
DL technique used: object classification, others (supervised DL)



Incorrectly picked components need to be identified Monitored using images of picked components



Magazine with components



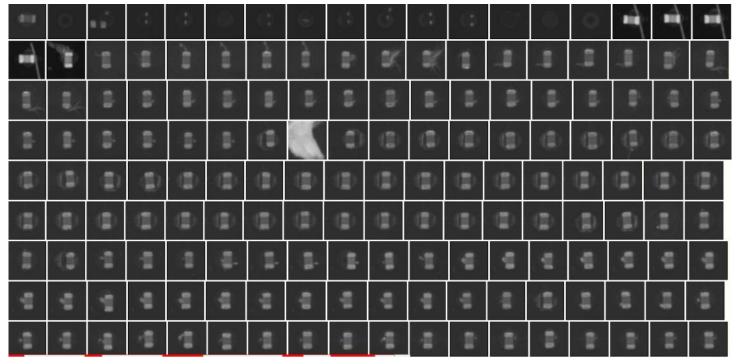
Robot arm picked a component (Image taken)



Component Mounted on PCB

This problem is difficult

Classical computer vision is not sufficient



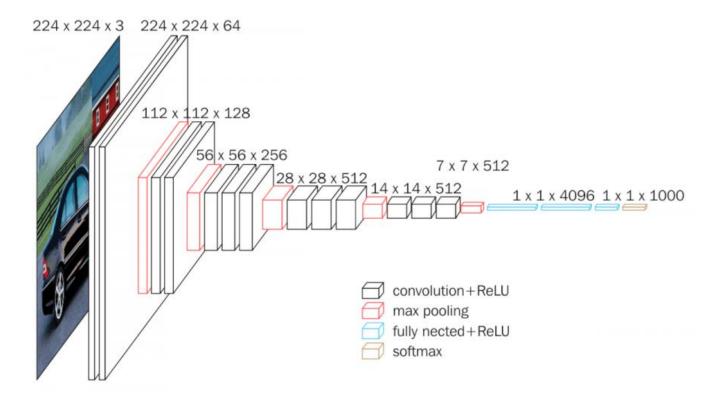


Historical & manual labels for supervised learning

Table 1 Quick Reference to all the Image Classes

Example	Errortag/pickErr?	Productiontag/ToolErr?			
	ОК	UNDEF	0	NOT PICKED	UNDEF
1	BILLBOARDED	UNDEF	2	STOP PRODUCTION	SOLDER PASTE NOT PICKED
•	TOMBSTONED	UNDEF	•	STOP PRODUCTION	SOLDER PASTE DPMO
•	CORNED PICK	UNDEF	*	STOP PRODUCTION	SOLDER PASTE
	WRONG PICK ANGLE	UNDEF		STOP PRODUCTION	ATTACHED
Sept.	UPSIDE DOWN	UNDEF		STOP PRODUCTION	WRONG PACKAGE
m	DAMAGED	UNDEF		STOP PRODUCTION	CORRUPTED IMAGE

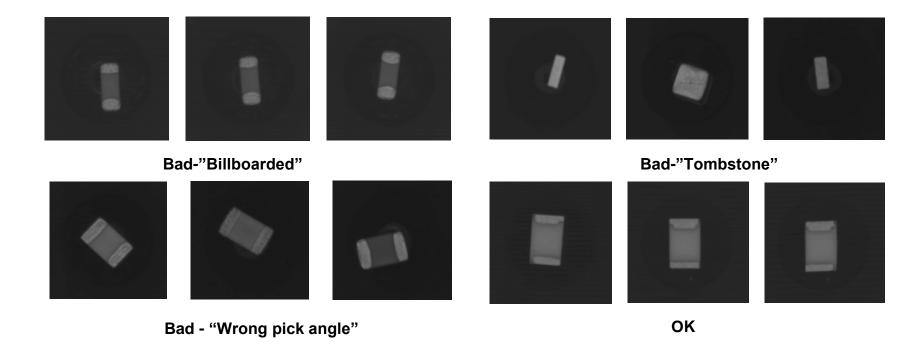
Object classification uses deep CNN



rps://neurohive.io/en/popular-networks/vgg16/

CNN based classifier was used to identify "Bad" PnP

Accuracy 99.76%, even on different machines

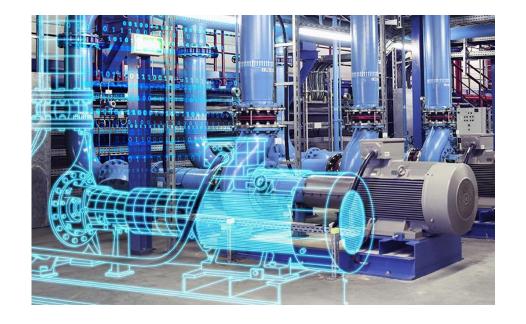




D2S: Digital twins creation with TrueMask^(R) DLK Deep Learning Toolkit

Digital twins can benefit from deep learning

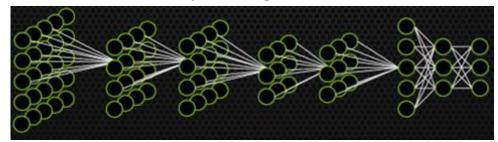
DL technique used: mixture models, GANs (semi-supervised DL)



DLK: GPU-accelerated platform for DL to generate digital twins

Digital Twins for Training Data Generation

Pre-trained Deep Learning Neural Networks



Verification



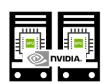
Mask Simulation

Wafer Simulation





Computational Design Platform (CDP)

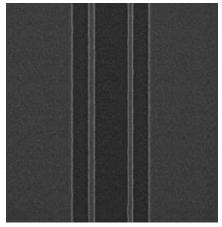


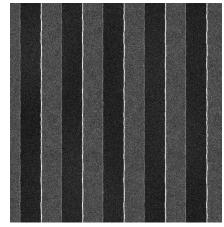




SEM digital twin is a must for all data analysis in mask shops and wafer fabs

- Almost all mask and wafer analysis is based on SEM images
- Getting mask and wafer SEM from mask shops and wafer fabs are difficult





Neural style transfer was seed idea for SEM digital twin

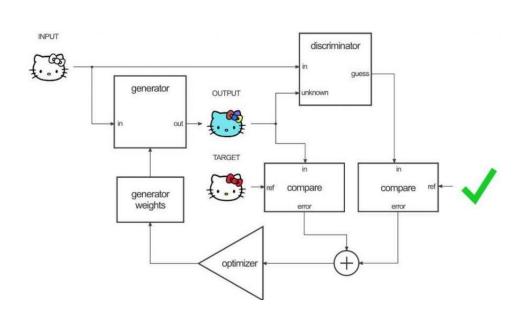


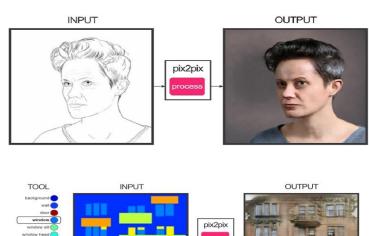
Picture of Dog

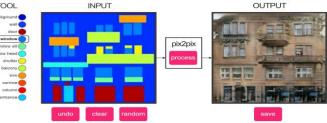
Style: Starry Night of Vincent van Gogh

New Artwork

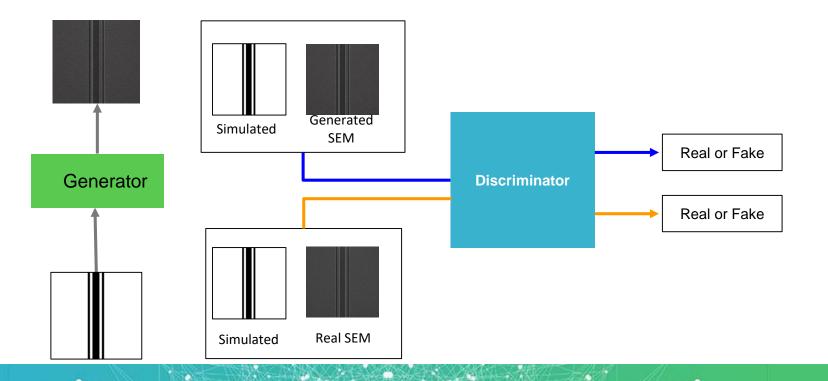
Generative Adversarial Networks (GANs) based Pix2Pix architecture was used finally



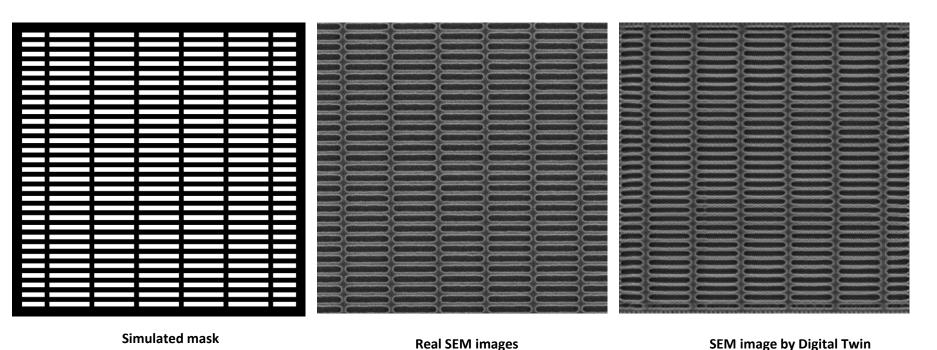




Generative Adversarial Networks (GANs) based Pix2Pix architecture was used finally



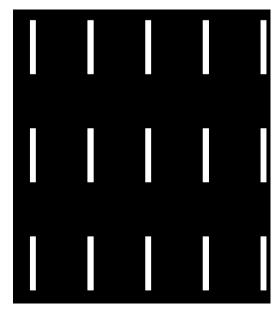
SEM images from TrueMask^(R) DLK SEM digital twin



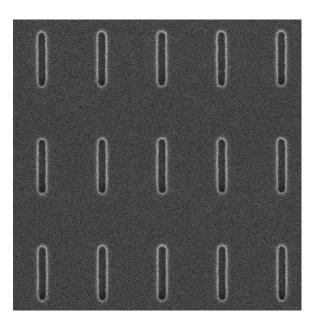


pattern

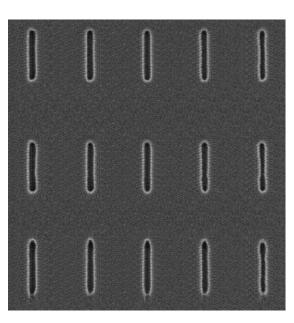
SEM images from TrueMask^(R) DLK SEM digital twin



Simulated mask pattern

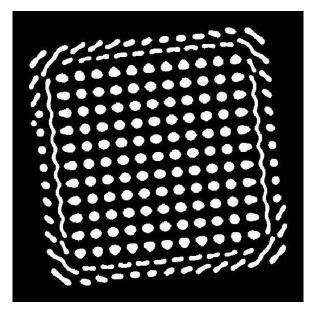


Real SEM images

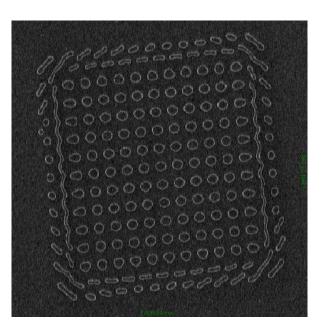


SEM image by Digital Twin

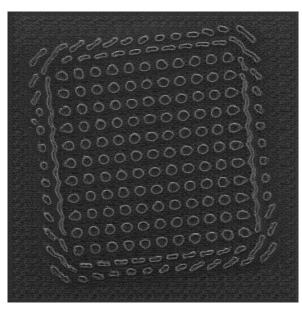
SEM images from TrueMask^(R) DLK SEM digital twin



Simulated mask pattern

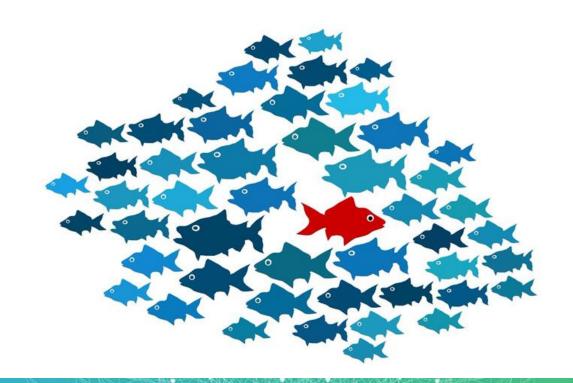


Real SEM images



SEM image by Digital Twin

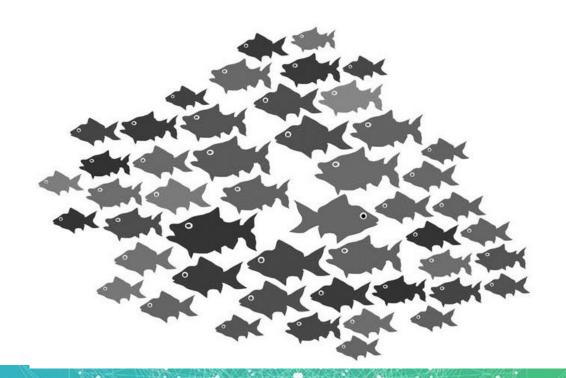
Humans can find an anomaly easily





How about now?

Still find anomaly?





And now?

DL performs great to find anomaly for huge data

